



















Features

TAC 2.0 Thermal Solution

Qualified for TAC 2.0, a mass ventilation hole side panel design strengthens thermal efficiency and cools down the entire system.

Cooling Fan

Optional 90mm auxiliary cooling fan at rear panel for better system cooling.

Tool-Free Installation and Easy Maintenance

Tool-free front panel, drive bays and I/O slots.

Side Panel Clips

The patented tool free installation side panel clips.

Stamped Motherboard Support

No MB standoffs installation required for faster MB installation.

Folded Edge

For safety installation. No sharp edges and debris.











* Available in Selected Regions Only

* Available in Selected Regions Only

* Available in Selected Regions Only

specifications

Case Size Mini Tower Chassis

External Drive Bays 5.25" x 2, 3.5" x 2 (Z670: 5.25" x 2, 3.5" x 1) **Internal Drive Bays** 3.5" x 1, 2.5" x 1 (Z670: 3.5" x 2, 2.5" x 1)

Front Ports USB2.0 x 2, HD Audio

Dimensions (HxWxD) 363 x 180 x 370m w/o Front Panel 14.3" x 7.1" x 14.6" 363 x 180 x 370mm

MB Form Factor Micro-ATX, Mini-ITX

I/O Expansion Slots PCI-E Expansion Slot x 4

Power Supply ATX 12V Form Factor, PSII Size

Thermal Solution • Supports 80mm or 90mm Rear Fan • Intel Certified TAC 2.0

Meets RoHS, CE and FCC Class B Requirements Safety

Security Padlock Loop / Kensington Slot

•80 or 90mm Rear Fan •eSATA Optional • Chassis Intrusion Switch • USB 3.0 x 2

•3.5" to 2.5" HDD/SSD Bracket



^{*} The actual product is subject to change without prior notice. In Win Development Inc. reserves the right to make final modifications.















